



2012 ASIA-PACIFIC International Symposium on Electromagnetic Compatibility - APEMC2012

May 21- 24, 2012

Resorts World Sentosa, Singapore

www.apemc2012.org

Call For Papers

Topical Meeting on Electromagnetic Compatibility of Integrated Circuits and Systems-on-Chip

The **Topical Meeting on the Design of 2D & 3D Integrated Circuits and Systems for Electromagnetic Compatibility** will be held in conjunction with 2012 Asia-Pacific International EMC Symposium (APEMC2012) in Singapore, from May 22 to 24, 2012. Presented papers are also published in the **IEEE Xplore Digital Library**. Topics of interest include, but are not limited to:

- Design of 2D and 3D system-on-chip (SoC) for EMC
- Hardware-software co-design and integration for IC EMC
- Emission and immunity-aware IC design
- ESD immunity techniques at IC level
- Signal and power integrities at IC level
- Combined effects of radiation and aging on IC EM sensitivity
- Harsh environment effects on IC EM sensitivity
- IC EMC for avionics and automotive real-time applications
- EMC-robust analog and mixed signal circuits
- RF ICs for EMC
- IC EMC measurement techniques
- IC EMC modeling techniques
- EMC-robust embedded software
- IC simulation tools and procedures for EMC
- IC standards and regulations for EMC

Important Dates:

Preliminary paper submissions
(2 pages in PDF format only) **January 6, 2012**

Notification of acceptance **February 5, 2012**

Final paper submission (4 pages max)
through the portal www.apemc2012.org **March 15, 2012**

All submissions must be electronic. Font embedding must be IEEE Xplore compatible. No hardcopies shall be accepted. Details are given on the symposium website: www.apemc2012.org

Topical Meeting Organising Chairs

Sonia Ben Dhia, LAAS CNRS, France
sonia.bendhia@insa-toulouse.fr

Fabian Vargas, PUCRS, Brazil
vargas@computer.org

Scientific Committee

- A. Boyer, LAAS CNRS, France
- A. Barić, FER, Croatia
- P. Besse, Freescale, France
- M. Coenen, EMC MCC bv, The Netherland
- C. Dueñas, Freescale, Brazil
- B. Deutschmann, Infineon, Germany
- F. Fiori, Polito, Italy
- E. Gatti, INTI, Argentina
- F. Hernandez, Univ. ORT, Uruguay
- R. Maltione, Freescale, Brazil
- C. Marot, EADS, France
- M. Ramdani, ESEO, France
- L. Pöhls, PUCRS, Brazil
- F. Silva, UPC, Spain
- T. Steinecke, Infineon, Germany
- B. Vrignon, Freescale, France
- O. Wada, Kyoto Univ, Japan
- X.C. Wei, Zhejiang Univ., China
- S. Yuan, FCU, Taiwan

Symposium Secretariat

Miss Ellen HENG
CMA International Consultants Pte Ltd
1 Liang Seah St
#02-12 Liang Seah Place
Singapore 189022
Tel: +65-6336 2328
EMCSingapore@cma.sg

